As a below hamed inventor, I declare that my residence, mailing address and citizenship are as stated below hame; I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME

of the application on which priority is claimed:

the specification of	which (che	eck applicable box(es)))
[] is attached her	reto.		
[X] was filed on A	April 1,	2004	as United States Application No. 10/814, 266
or PCT Interna	ational App	olication No.	
[] and was amen	ded on		
I hereby state that	I have revi	iewed and understan	d the contents of the aboveidentified specification, including
the claims, as ame	nded by an	y amendment referre	ed to above.
I acknowledge the	duty to disc	close information wh	ich is material to patentability as defined in 37 CFR 1.56.
I hereby claim fore	ign priority	y benefits under 35 U	J.S.C. 119(a)-(d) or 365(b) of any foreign application(s) for
patent or inventor'	's certificate	e, or 35 U.S.C. 365(a)	of any PCT International application which designated at
least one country o	other than t	the United States, lis	ted below and have also identified below any foreign
application for pate	ent or inver	ntor's certificate, or P	CT International application having a filing date before tha

				Priority	
Country	Category	Application Number	Filing Date	Claim	
Japan	Patent	2004-006927	January 14, 2004	Yes	

I hereby appoint as my attorneys, with full power of substitution and revocation, to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: the practitioners at:

Customer Number: 22850

of Oblon, Spivak, McClelland, Maier & Neustadt, P.C.. Please address all correspondence and telephone communications to the address and telephone number for this Customer Number.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I declare further that my citizenship,	residence and mailing address a	are as stated below	next to my name:
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Italh Oul

MAY. 1 O. 2004

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Date: